



P8000IG6









Most Advanced Platform for Al and HPC Workloads

Highlights

- Modular architecture to provide customer the best performance platform
- Best GPU-GPU Communication with Nvidia NVIink and NVswitch Architecture on H100/200 8 GPU HGX architecture
- DDR5 and PCle gen 5.0 ready platform Design
- Inventec-designed switchboard provides maximum bandwidth for GPU direct RDMA
- Increase power efficiency and reliability by decoupling 12V and 54V power source
- Great serviceability and assembly with the Modular Design

As the year of Al blooms, all major tech companies focused on Al products. To go with the Al tide, the Al servers, the heart of all Al products, are more significant than ever. Inventec P8000IG6 was born to solve the eager need for Al product producers. With its extreme flexibility and comprehensively considerate design, it will be a powerful weapon for our customers to approach the future Al demand.

An Extremely Flexible 8U GPGPU server

P8000IG6's modular architecture provides customers with the best performance platform. To fulfill diverse customers' requests, P8000IG6 uses Intel Eagle stream platform CPUs – Sapphire Rapids and Emerald Rapids, as its host node, and it adapts not only the NVIDIA H100/H200 HGX 8 GPU but also the H-Next HGX 8 GPU. Moreover, Inventec offers different thermal SKUs including Air-Cooling and Liquid-Cooling solutions to apply the most efficient performance.

Comprehensively Considerate Design

Inventec P8000IG6 has the best GPU-GPU communication with Nvidia NVIink and NVswitch architecture on H100/200 8 GPU HGX architecture. In addition, to achieve the system's best performance, the Inventec-designed switchboard bridges the Host node and the GPU node efficiently and offers maximum bandwidth for GPU direct RDMA. Moreover, to enhance power efficiency and reliability, P8000IG6 equips 12V and 54V power sources to supply the Host node and GPU module individually and decouples 12V and 54V power sources to avoid ripple effect.



Great Serviceability with the Modular and **Tool-less Design**

A modular and tool-less design offers a comfortable maintenance experience for our customers, especially the way Inventec designs P8000IG6 with trays, modular, and tool-less design. The P8000IG6 separates the Host node and the GPU node with different trays and creates several modules for the key parts, such as fans, power supply, NIC, and others, that give our customers a much more comfortable way to maintain the specific parts.



P8000 G6 Nvidia HGX GPU Server

Positioning	EIA 310, 19"
Form Factor	8U Rackmount W x H x D: 448x 352x 850 mm (17.63x 13.85x 33.46inch)
GPU Module	Option(1) 8 x Nvidia H100/H800/H200,SXM5 GPU Option(2) 8 x Nvidia B100 (Umbriel),SXM6 GPU
Motherboard	Intel EGS CPU up to 385W
PCIe Slot (from MB)	Option(1) 1x FHHLDW Option(2) 2x FHHLSW Option(3) 1x OCP 3.0 SFF + 1x FHHLSW
PCIe Slot (from Switch)	8 x Low Profile card (PCleG5x16)
Storage (from Switch)	8 x U.2 NVMe SSD bays
Storage (from MB)	4 x U.2 NVMe SSD bays from CPU 2 x M.2 SATA SSD or NVMe SSD
Management Port	1 x RJ45 for BMC(AST2600) remote management
Cooling	Option(1) Air cooling Option(2) Liquid cooling
Power Supply	3300W 54V PSU, support 3+3 redundancy 2400W 12V PSU, support 1+1 redundancy
Fan	10 x 8086 Fans for GPU cooling 6 x 6056 Fans for CPU cooling

About Inventec Data Center Solutions (Inventec EBG)

Inventec Data Center Solutions (Inventec EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems in Inventec Corporation. Over decades, Inventec EBG has been the key server system supplier of the global branding clients.

Inventec Corporation (TAO)

No.88, Dazhi Rd., Taoyuan Dist., Taoyuan City 33068, Taiwan Tel: 886-3-390-0000 Fax: 886-3-376-2370 Email: TAOproductsupport@inventec.com



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